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Amendments to the Specification

Please replace the paragraph at page 1, lines 11-22 with the following amended paragraph:

--As circuit density continues to increase, the testing of SOC (System On a Chip) products becomes ever more important. Such testing is provided to determine whether electrical characteristics of the products operate normally, while the operating environment varies. For example, the circuit under test can be subject to an HVS (High Voltage Stress) test based on a gradually varied use range of the products and subject to [[a]] an extreme environment test, e.g., of high temperature, low temperature and very low temperature. Especially, in the test involving the ranging temperature environment, varying between a high temperature and a very low temperature, the test ensures the practical use of the product.--

Please replace the paragraph at page 3, lines 1-4 with the following amended paragraph:

--The test head part 14 includes a mounting member 14a on an upper face circumference thereof, the mounting member 14a ~~being for~~ electrically connecting the test board 20 with channel terminals 12a of the channel cards 12.--

Please replace the paragraph at page 7, lines 3-9 with the following amended paragraph:

--It is therefore an object of the present invention to provide an integrated circuit test system and method to prevent samples from being influenced by frost in a very low temperature environment, to shorten the exchange time of samples for a test through a continuous exchange, and ~~the prevent protect~~ the sample and respective components electrically connected to the sample[,,] from damage.--